L Number	Hits	Search Text	DB	Time stamp
1	2408	pad and area and (solder adj ball) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/28 10:56
-	24	(die adj pad) and PCB and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 14:29
-	17	(("5280192") or ("5579207") or ("6072233") or ("6180881") or ("5872025") or ("6093029") or ("5963430") or ("6313522")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 14:54
-	0	(metal adj peg) and (printed adj circuit adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 14:55
-	111	metal adj peg	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 14:56
-	1	(metal adj peg) and packaging	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 14:57
-	7	(metal adj peg) and (die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 15:39
-	210	257/697.ccls. and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 17:09
-	4317	(chip die) and wiring and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/07 17:10
-	46	((chip die) and wiring and ball) and (circuit adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 10:37
-	9	(("6201292") or ("6247229") or ("6025640") or ("6281047")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 17:08
-	4	(("6069396") or ("6232636")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 10:58
-	8	(("6229205") or ("6204090") or ("5965947") or ("6157074")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 13:44

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-	970	line adj mask	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 13:45
-	0	(line adj mask) and (insulating adj paint)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 13:45
-	0	(line adj mask) and paint and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 13:46
-	455	(line adj mask) and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 13:46
-	10	((line adj mask) and circuit) and (screen adj printing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 10:29
-	22	mask near5 paint and thermally	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/08 17:09
-	974	257/718-720.ccls. and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 10:34
-	3	257/718-720.ccls. and (heat adj sink) and (die adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 10:33
-	41	(257/718-720.ccls. and (heat adj sink)) and encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 10:40
-	3	("5291062").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 10:48
-	329	(bond adj pad) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 10:49
-	189	(bond adj pad) and (heat adj sink) and 257/$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/11 10:50
-	78	257/697,711,737-738,666.ccls. and (wiring adj connect$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 16:13
-	70	438/15,106,112,121,124,612.ccls. and (metal adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 16:38

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